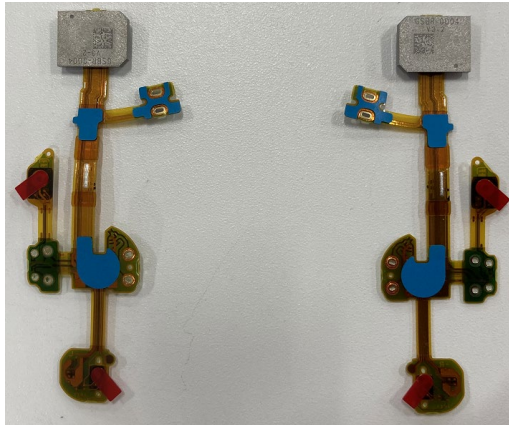


Bluetooth Module(GSBR-004)

L

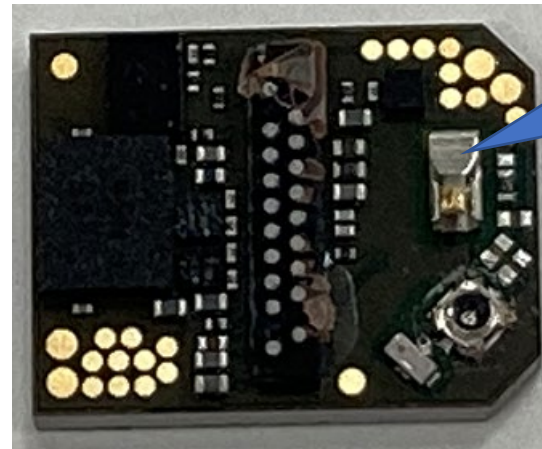
R



Top

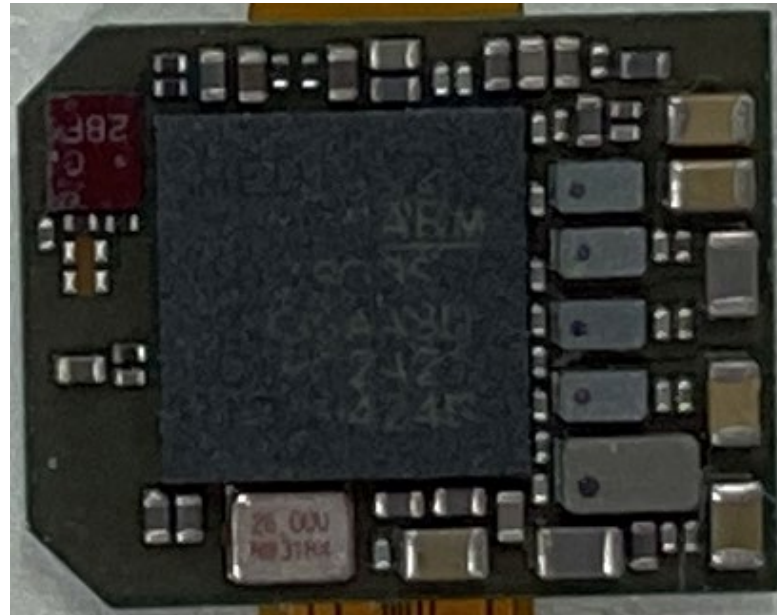
SiP(System in a Package)
The Bluetooth IC(MT2833) is built into the SiP and Sealed with resin
The resin cannot be removed

Bottom

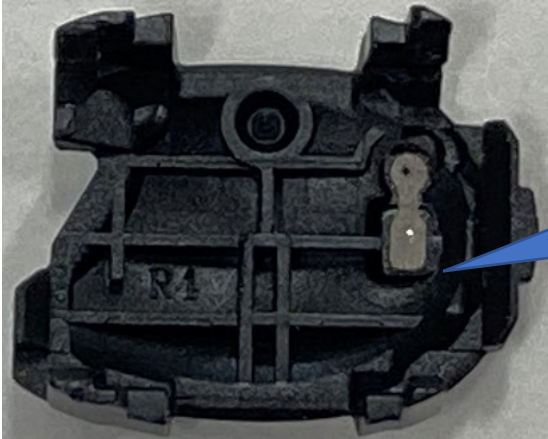


Spring
connector
to Antenna

Top side
Before Resin molding

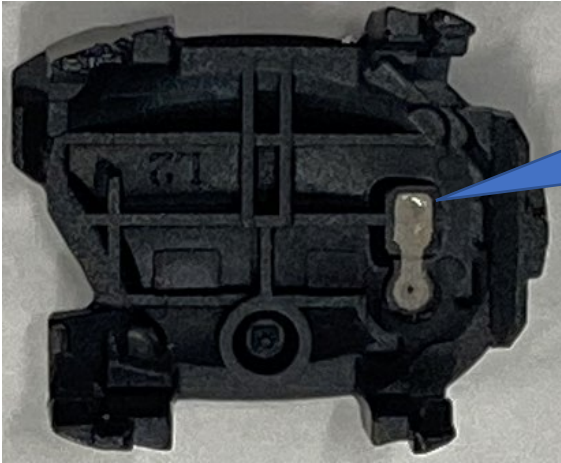


Antenna R



Contact point to Spring connector

Antenna L



Contact point to Spring connector